

Applicant: Hee-Jin Park, Tae-Jin Park and Eun-Chul Ahn
Serial No. not yet assigned Examiner: not yet assigned
Filing Date: November 20, 2003 Art Unit: not yet assigned
Title: STACKED CHIP PACKAGE WITH HEAT TRANSFER WIRES

INFORMATION DISCLOSURE CITATION
FORM PTO-1449 (Modified)

U.S. PATENT DOCUMENTS

<u>Exam</u> <u>Init</u>	<u>Ref</u>	<u>Document</u> <u>Number</u>	<u>Issue</u> <u>Date</u>	<u>Name</u>	<u>Class</u>	<u>Sub</u> <u>Class</u>
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<u>Exam</u> <u>Init</u>	<u>Ref</u>	<u>Document</u> <u>Number</u>	<u>Publication</u> <u>Date</u>	<u>Country</u>	<u>Name</u>
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_____	_____	English language of Korean Abstract for Korean Patent Publication No.2002-36191, published 5/16/2002.

Examiner: _____

Date Considered: _____